

Title: Microcap Wafer Bonding Method And Apparatus Inventor: R. Shane Fazzio Attorney Docket: 10030899-1

REPLACEMENT SHEET 1/2

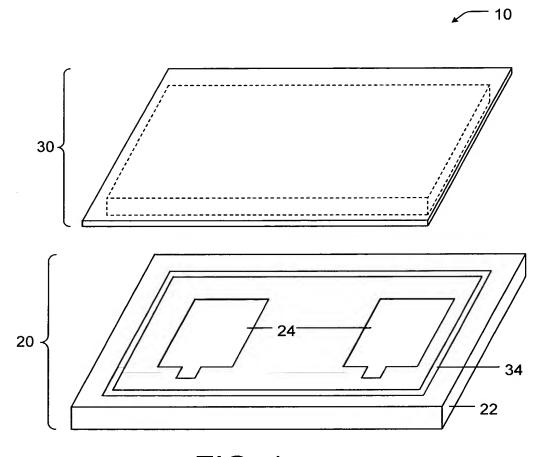


FIG. 1 (Prior art)

